

Selectively Patterned Masks: Structured ASIC with Asymptotically ASIC Performance

Donkyu Baek, Insup Shin, Seungwhun Paik,
and Youngsoo Shin

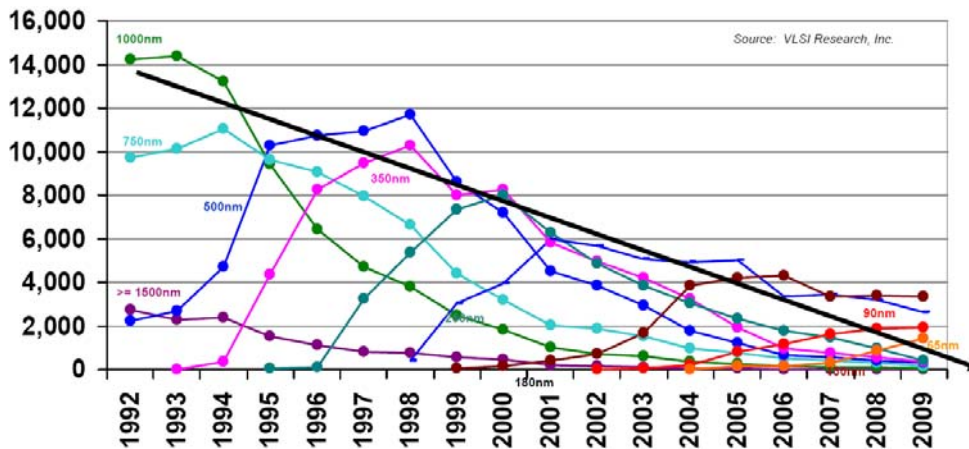
Dept. of EE, KAIST, KOREA

Outline

- Introduction
- Selectively patterned masks (SPM)
 - Concept
 - Pattern transfer process
 - Analysis: mask cost, throughput
- Structured ASIC using SPM
 - Tile design
 - Logic synthesis
 - Routing architecture
- Experimental results
- Conclusion

ASIC Has Been Slowed Down

- New design starts decrease
- Global alliance of foundries emerges
- **Increasing mask cost** is one of reasons



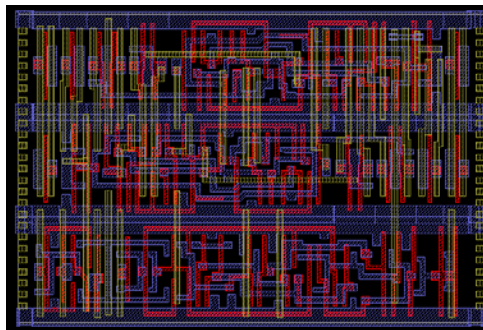
Process (μ)	2.0	0.8	0.6	0.35	0.25	0.18	0.13	0.10
Single Mask cost (\$K)	1.5	1.5	2.5	4.5	7.5	12	40	60
# of Masks	12	12	12	16	20	26	30	34
Mask Set cost (\$K)	18	18	30	72	150	312	1,000	2,000

EETimes, 2002

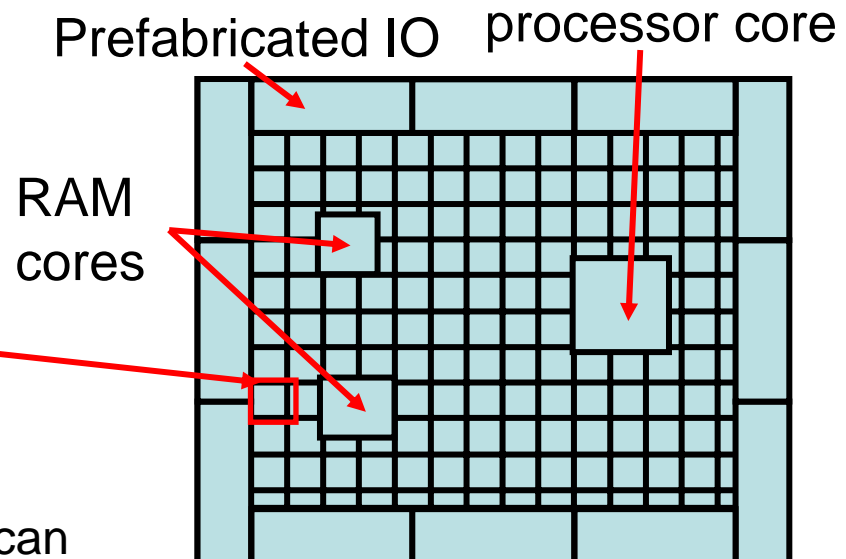
Structured ASIC

- Programmable device: a solution for mask cost
- Structured ASIC
 - Gate array has evolved into structured ASIC
 - Makes only contact/via masks for programming
↔ all metal and via masks in gate array

[N. Shenoy, DAC 2004]

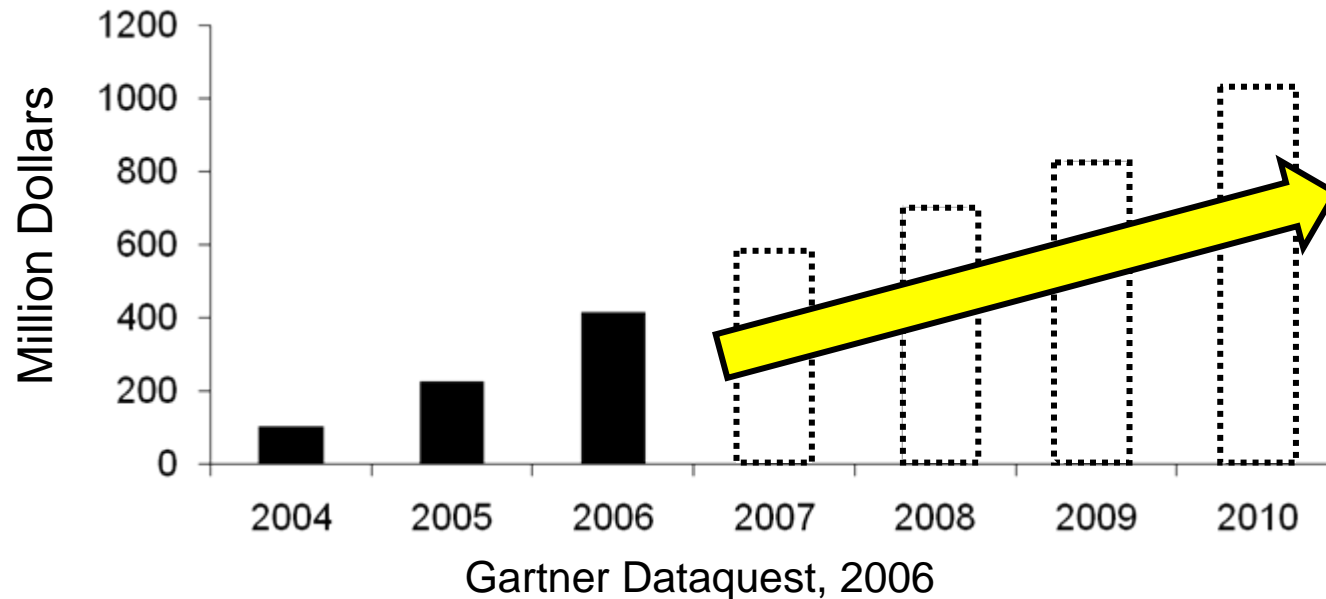


- 2 MUX tree, 2 local inverters
- A F/F with set/reset/enable/scan



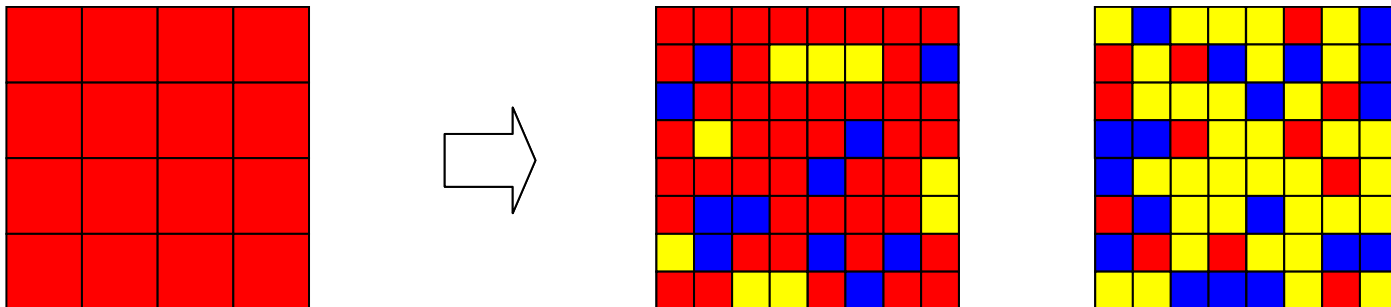
Structured ASIC

- Introduced in 1999
- Big success was expected
- Many companies jumped in the business in early 2000
- Not very successful
 - Not competitive to ASIC (**area: 3 ~ 7 times, delay: 2 ~ 6 times**)



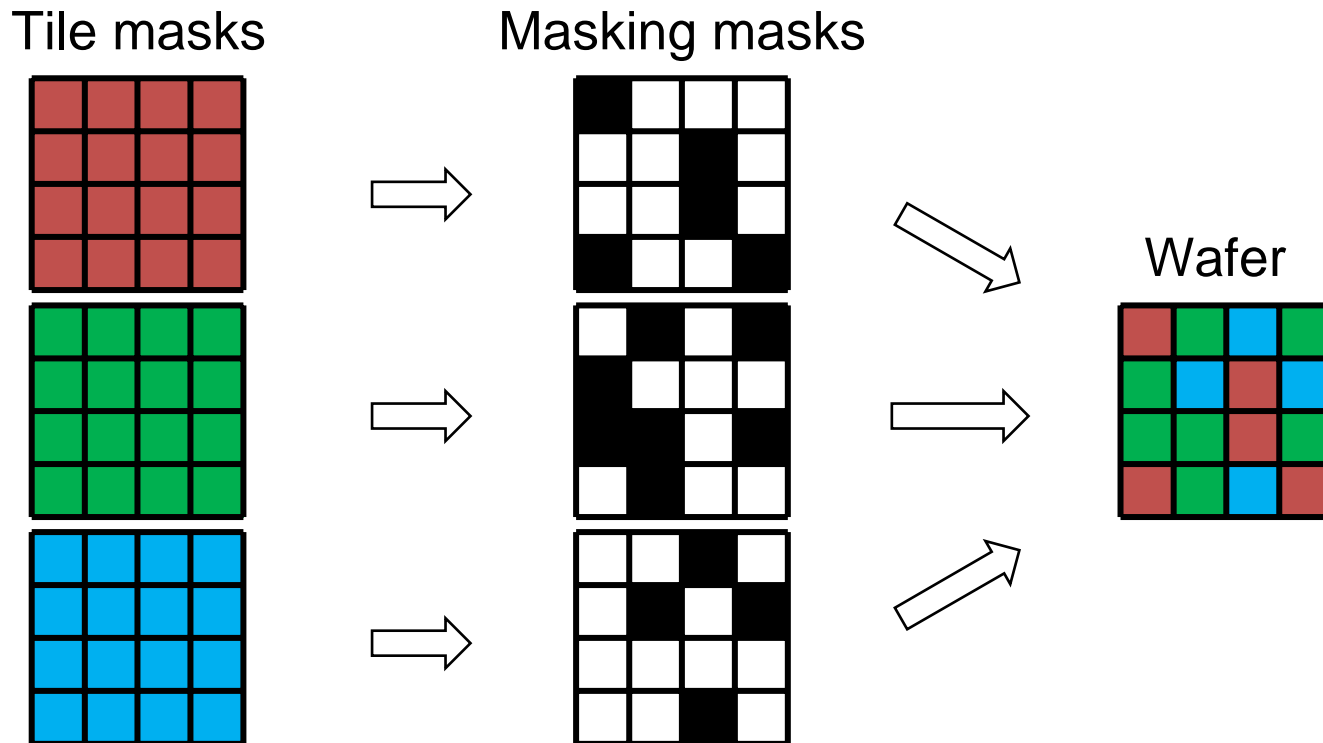
Structured ASIC

- Current SA: only one type of “tile”
 - Tile must be designed to implement any logic: too much redundancy
- **Is it possible to have multiple tiles?**
 - Different designs would need different mix of tiles
→ Have to make ALL masks!



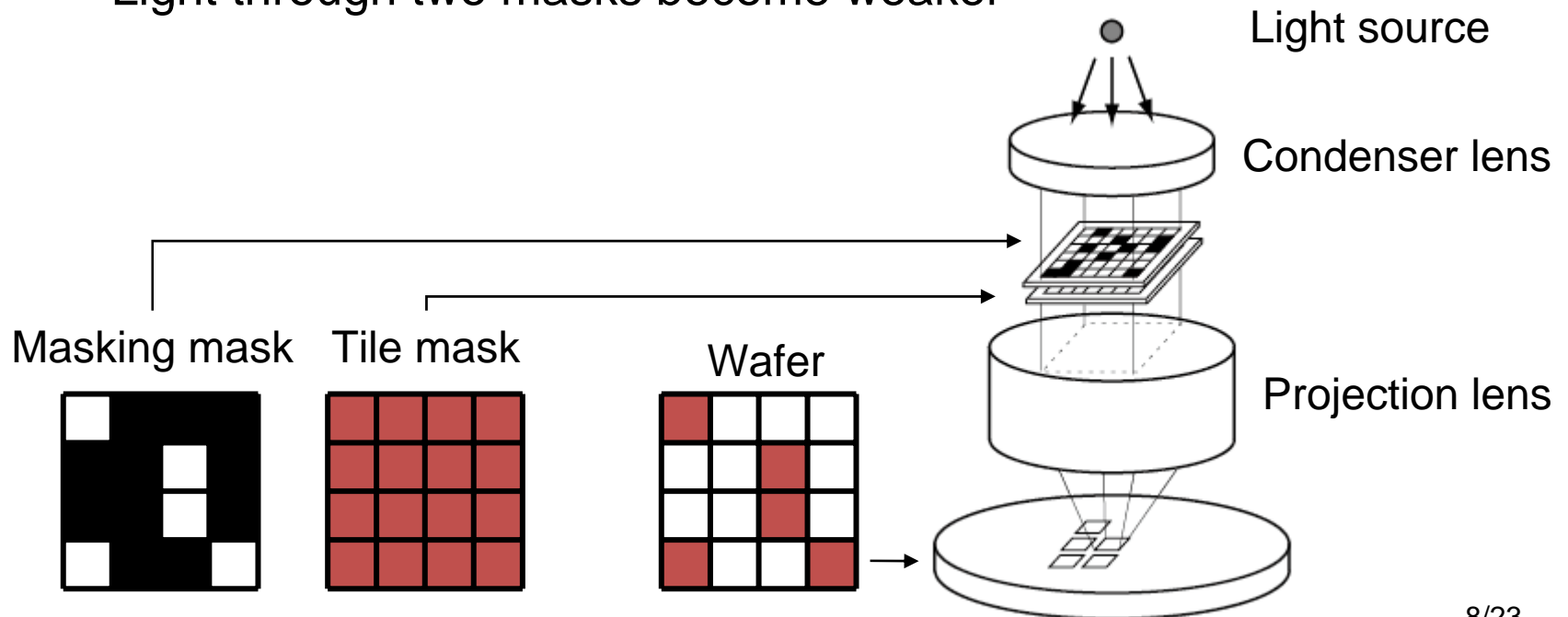
Selectively Patterned Masks (SPM)

- Tile masks: homogeneous just like SA, but more than one tiles
- **Masking masks:** used to selectively pattern tiles



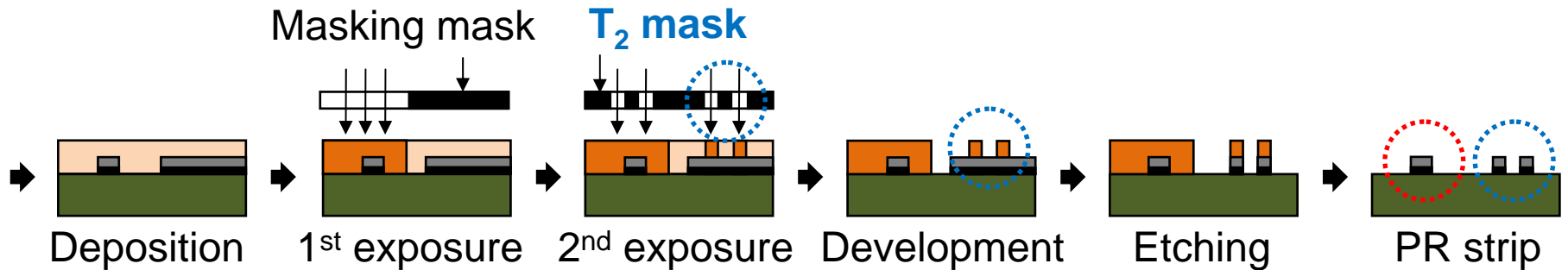
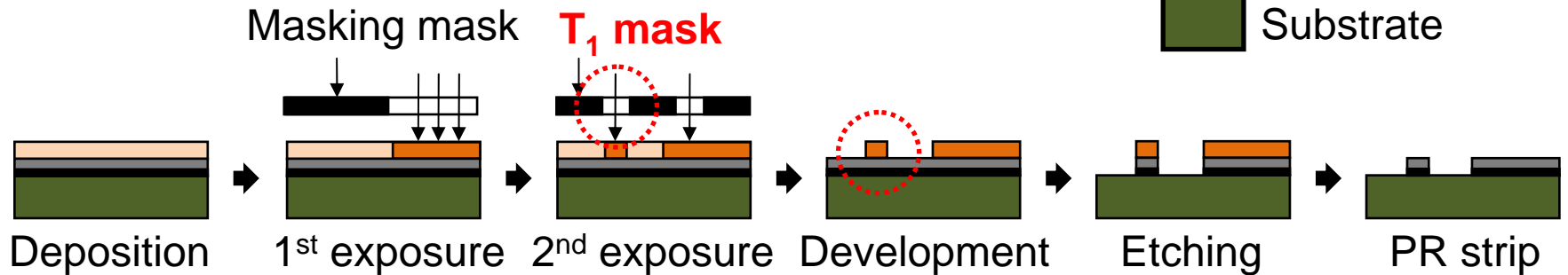
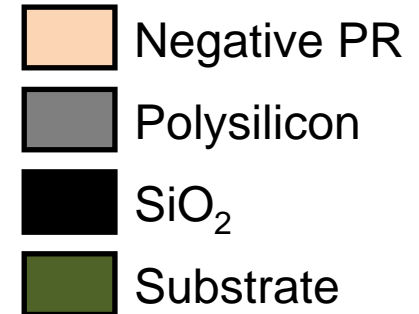
Selectively Patterned Masks (SPM)

- How to selectively pattern? Method I: tile and masking masks together during lithography
- **But, practical limitation...**
 - Current lithography equipment does not support
 - Light through two masks become weaker



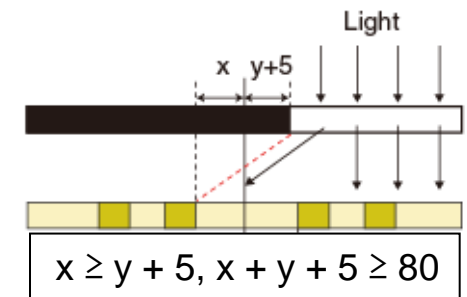
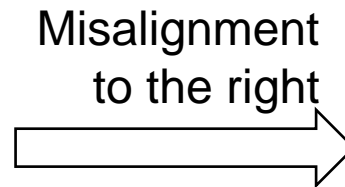
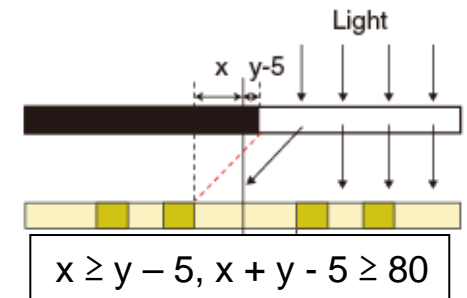
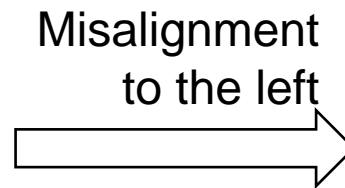
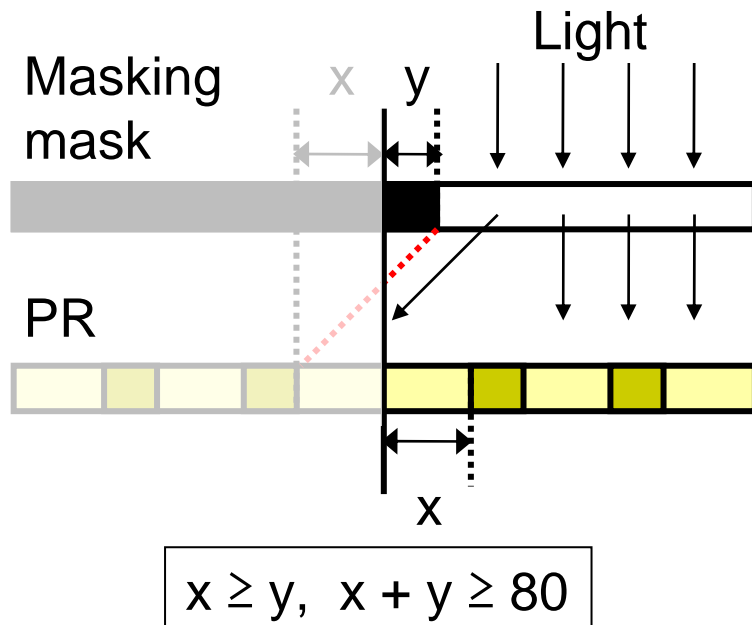
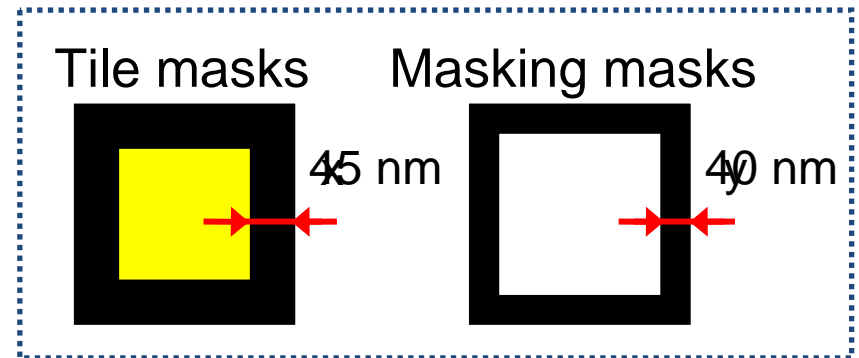
Selectively Patterned Masks (SPM)

- Method II: **double exposure**



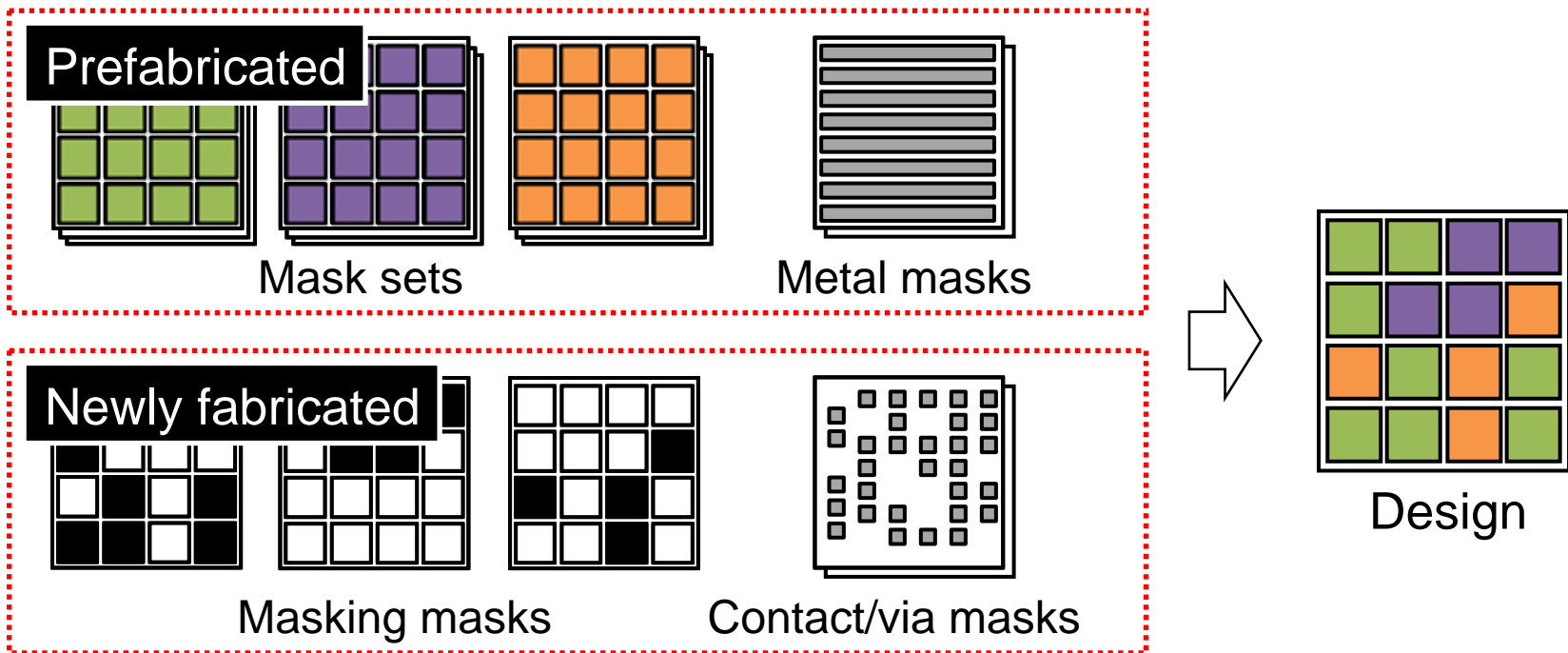
Mask Design in Double Exposure

- **Boundary margin** to accommodate
 - Light diffraction
 - Mask misalignment



Structured ASIC Using SPM

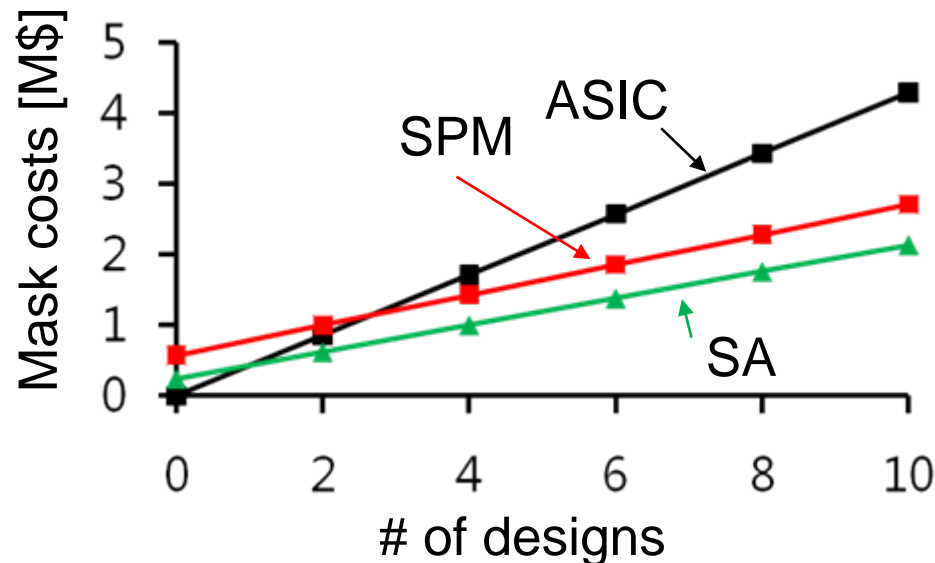
- **Mask sets, metal masks:** pre-fabricated
- **Contact/via masks:** fabricated for each design, used to program tiles & make connection
- **Masking masks:** fabricated for each design, but cheap



Analysis of Mask Cost

- Cost model is similar to that of standard SA

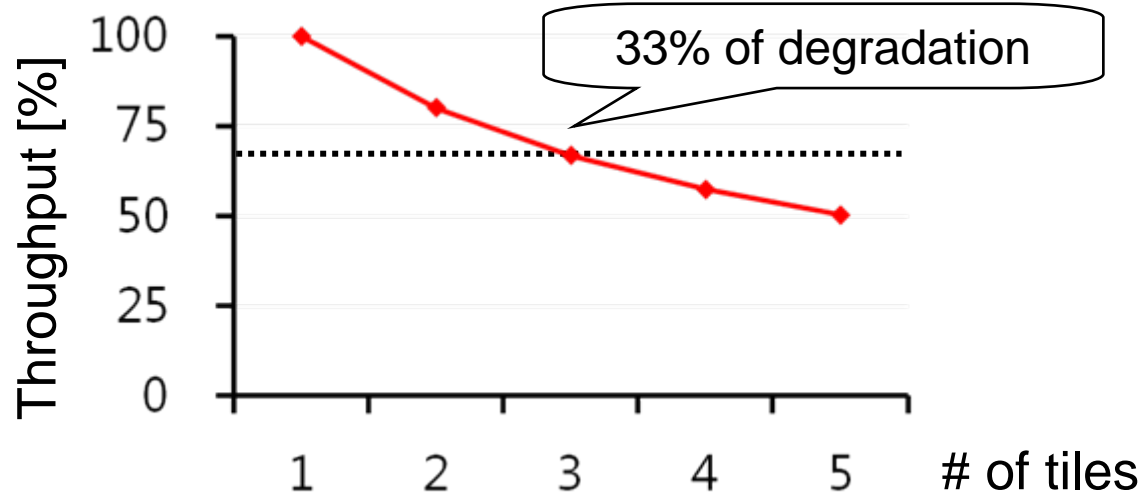
	Pre-fabricated	Newly fabricated
ASIC		All masks
Standard SA	One tile mask set	Contact & via masks
SA with SPM	Multiple tile mask sets	Contact & via masks + Masking masks



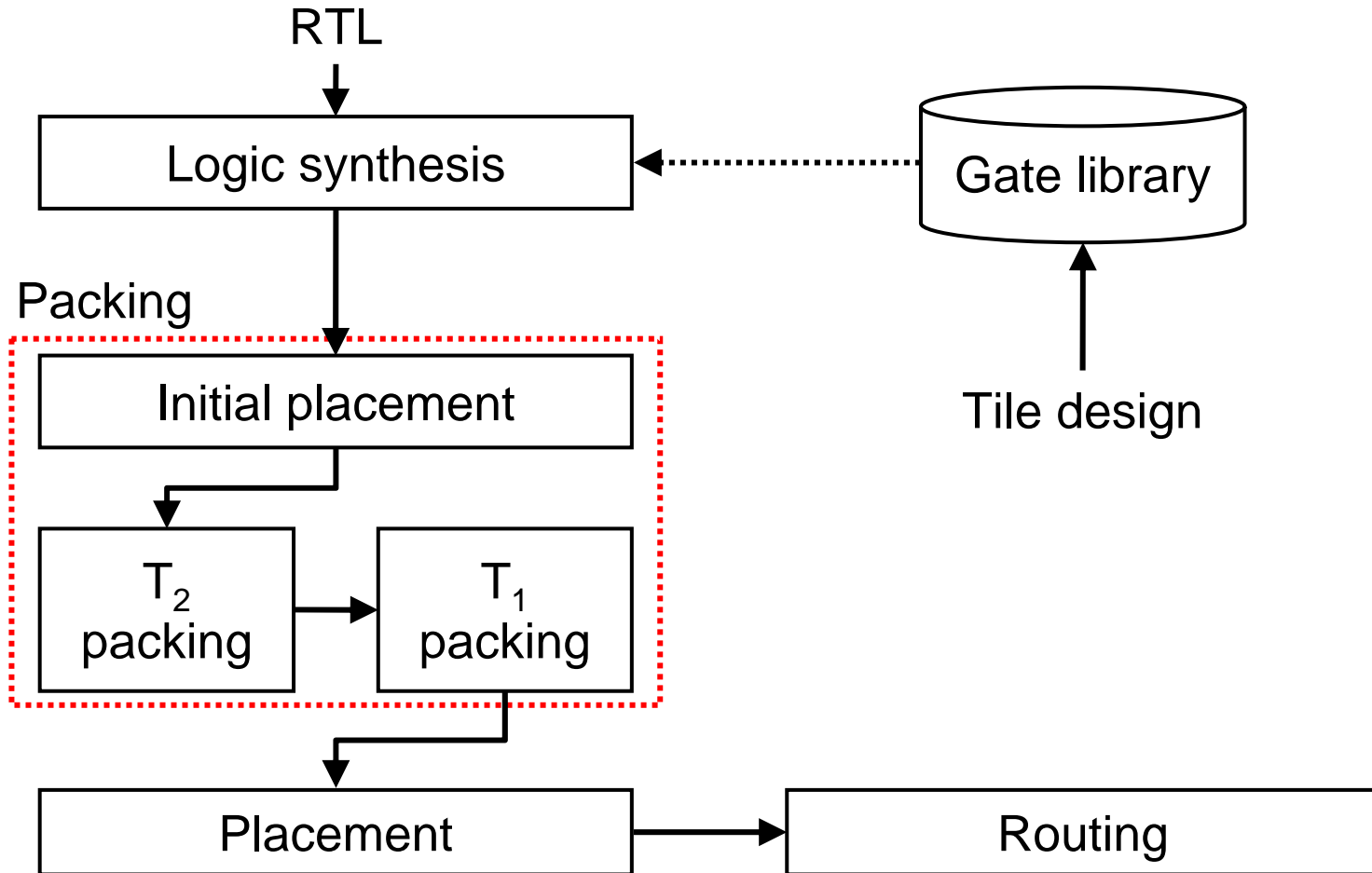
Analysis of Manufacturing Throughput

- Use of masking masks and multiple tiles increase manufacturing time

	Exposure	Etching
Standard patterning	One time	One time
Selective patterning	# of tiles \times 2	# of tiles



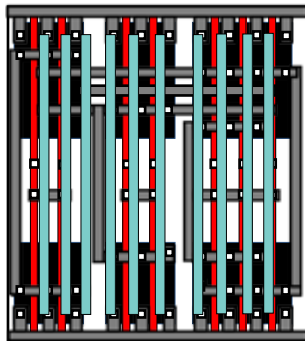
Structured ASIC Using SPM



Tile Design

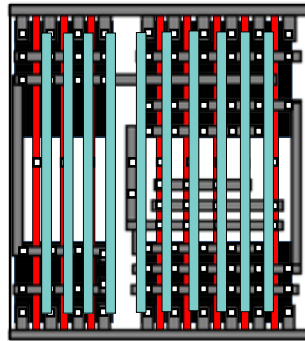
- Three tile architectures
 - T_1 : three basic logic gates
 - T_2 : two complex gates
 - T_3 : F/F (with set/reset)

INV, NOR2,
AND2, ...



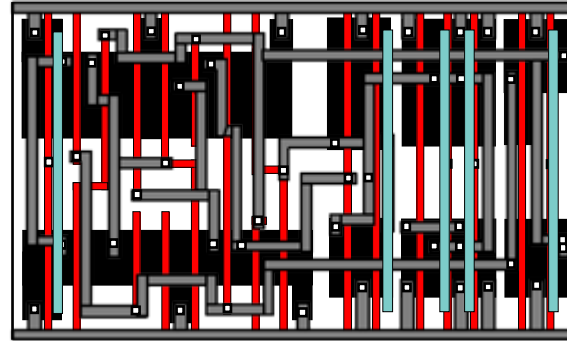
T_1

AOI221,
INV_X4, ...



T_2

Flip-flop

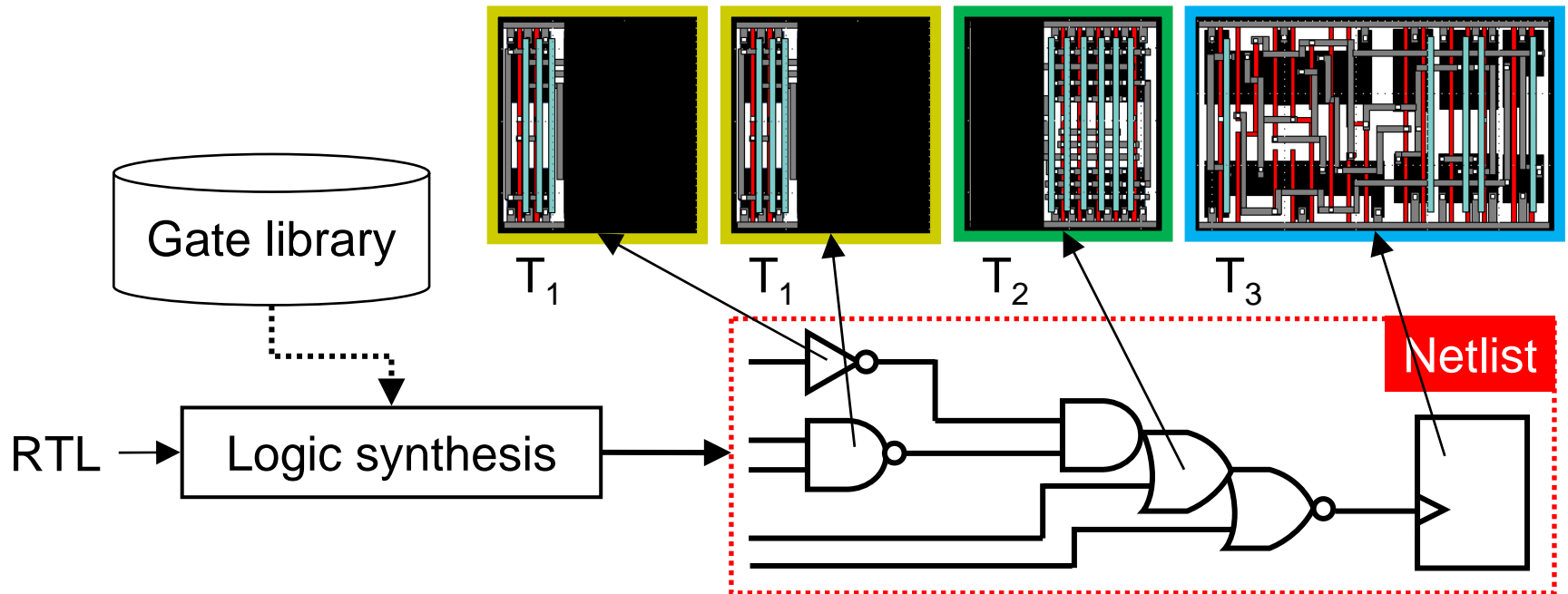


T_3

- Active
- Poly
- Metal1
- Contact
- Metal2

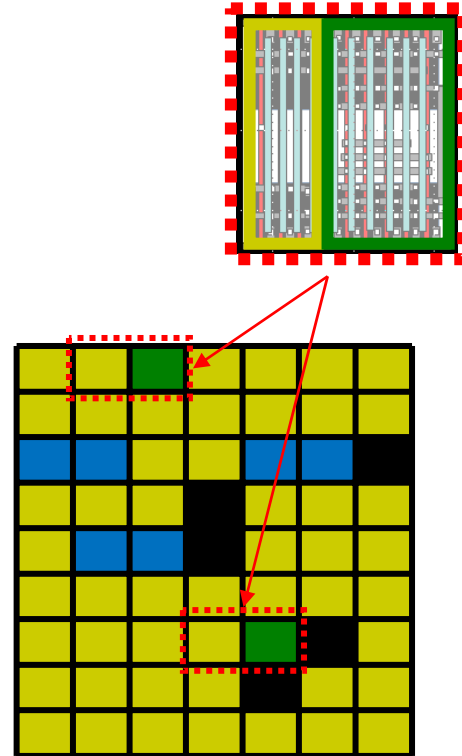
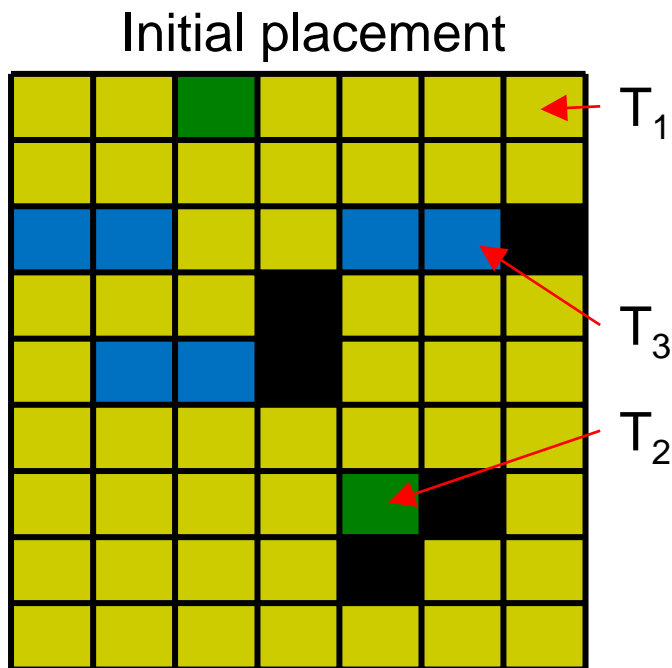
Logic Synthesis

- **Gate library**: models each “gate” (NOT tile)
- **Logic synthesis**
 1. Initial netlist is made such that each gate occupies one tile



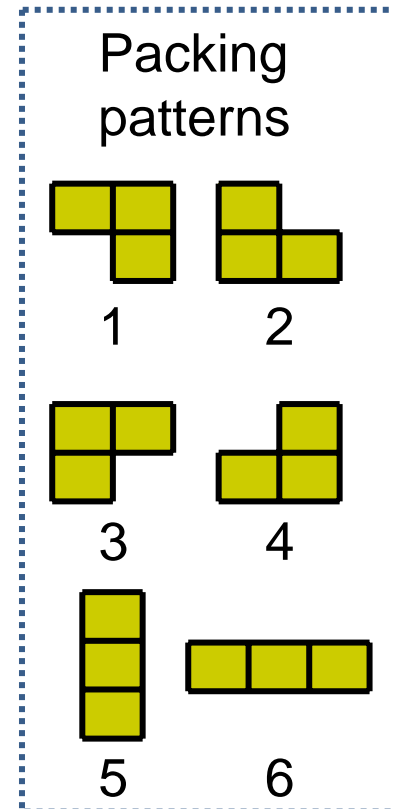
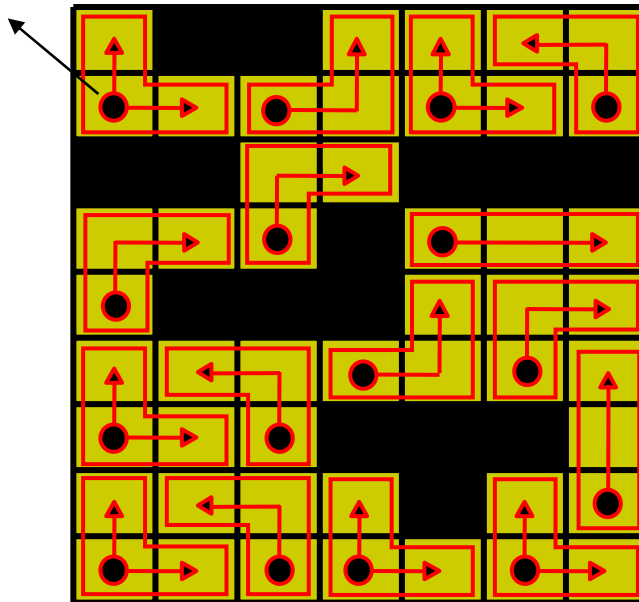
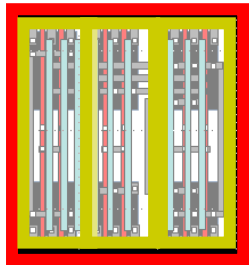
Logic Synthesis

2. Initial placement
3. Locate T2 → merge with nearest T1



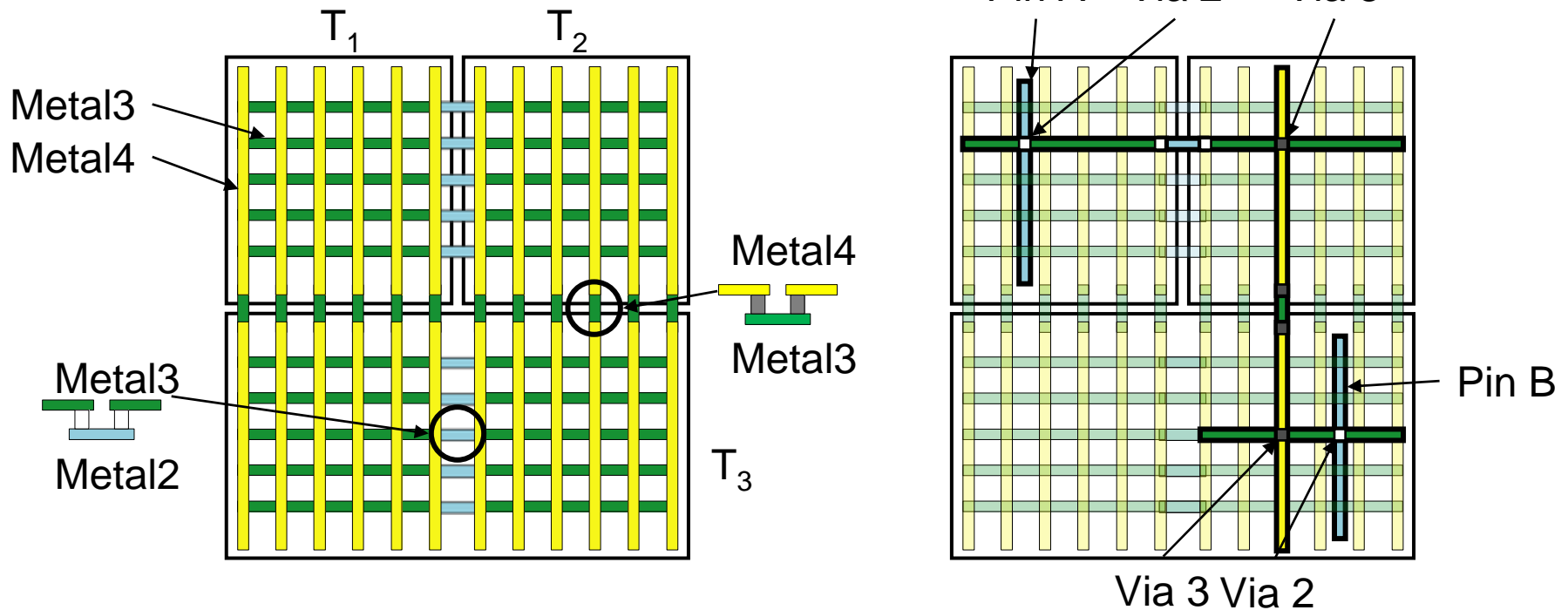
Logic Synthesis

4. Merge adjacent “three” T_1 s \leftarrow scan tiles from bottom-left to upper-right of placement



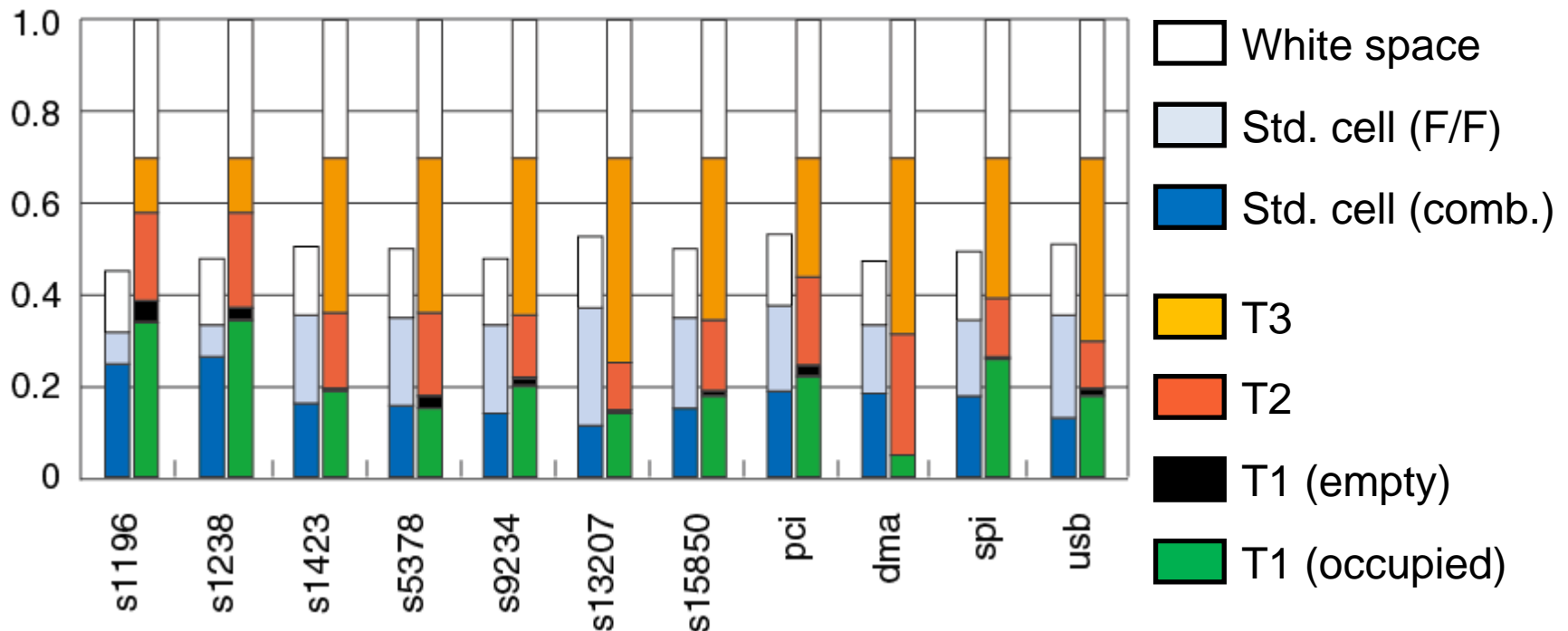
Routing Architecture

- **A grid** (made of M3+M4) is placed on top of each tile (two grids for T3)
- Programmable via is used for inter-tile connection



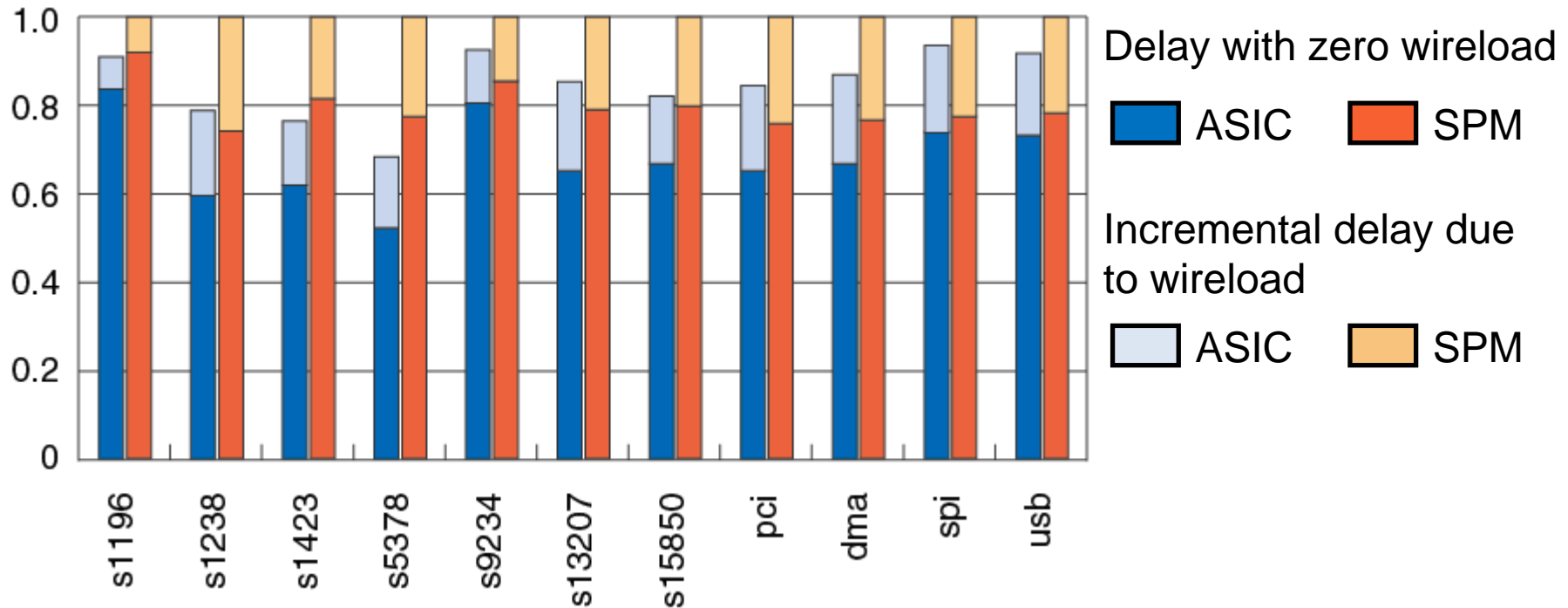
Experimental Results

- Area-optimized design
 - SPM/ASIC = 2 \leftrightarrow 3 ~ 7 in conventional SA
 - Why area increases? \rightarrow tile height & tile utilization



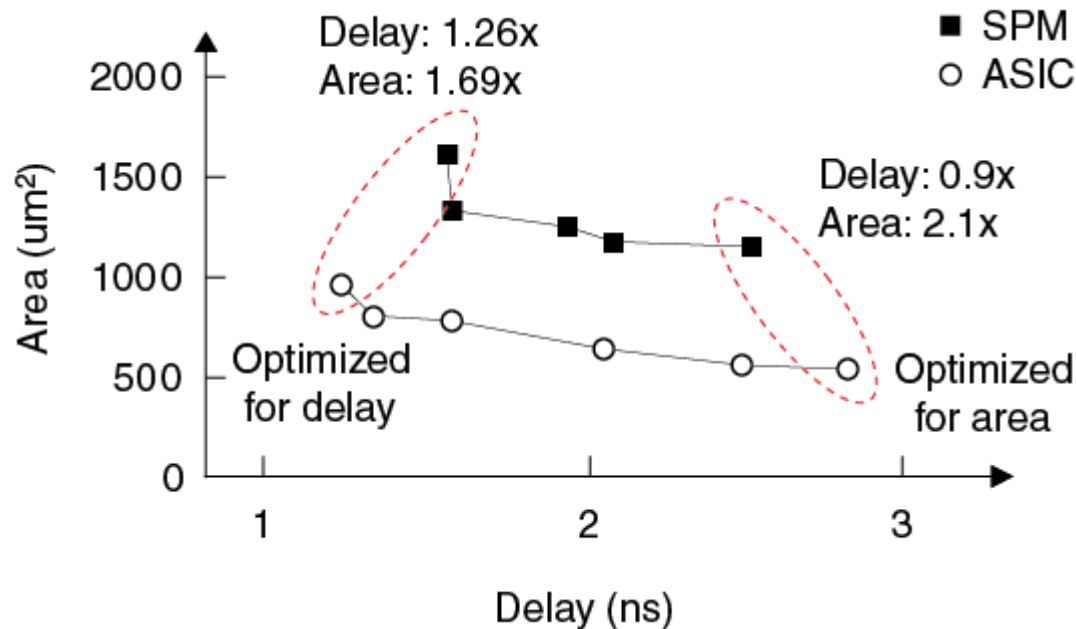
Experimental Results

- Delay-optimized design
 - SPM/ASIC = 1.2 \leftrightarrow 2 ~ 4 in conventional SA
 - Why delay increases? \rightarrow lack of gates & routing arch.



Experimental Results

- Design space (area vs. delay curve)
 - Delay opt. \rightarrow SPM/ASIC = 1.26 (delay), 1.69 (area)
 - Area opt. \rightarrow SPM/ASIC = 0.9 (delay), 2.1 (area)
 - Why large gap occur? \rightarrow lack of gates & tile regularity



Conclusion

- Current structured ASIC (SA)
 - Performance limited due to “regularity”
- SPM
 - Allows “irregular” structured ASIC with similar mask cost as SA
 - Prototype SA using SPM was demonstrated
- Future works
 - Logic synthesis
 - Routing algorithm